

GLITCH-FREE CLOCK MULTIPLEXER

ICS580-01

Description

The ICS580-01 is a clock multiplexer (mux) designed to switch between two clock sources with no glitches or short pulses. The operation of the mux is controlled by an input pin but the part can also be configured to switch automatically if one of the input clocks stops. The part also provides clock detection by reporting when an input clock has stopped.

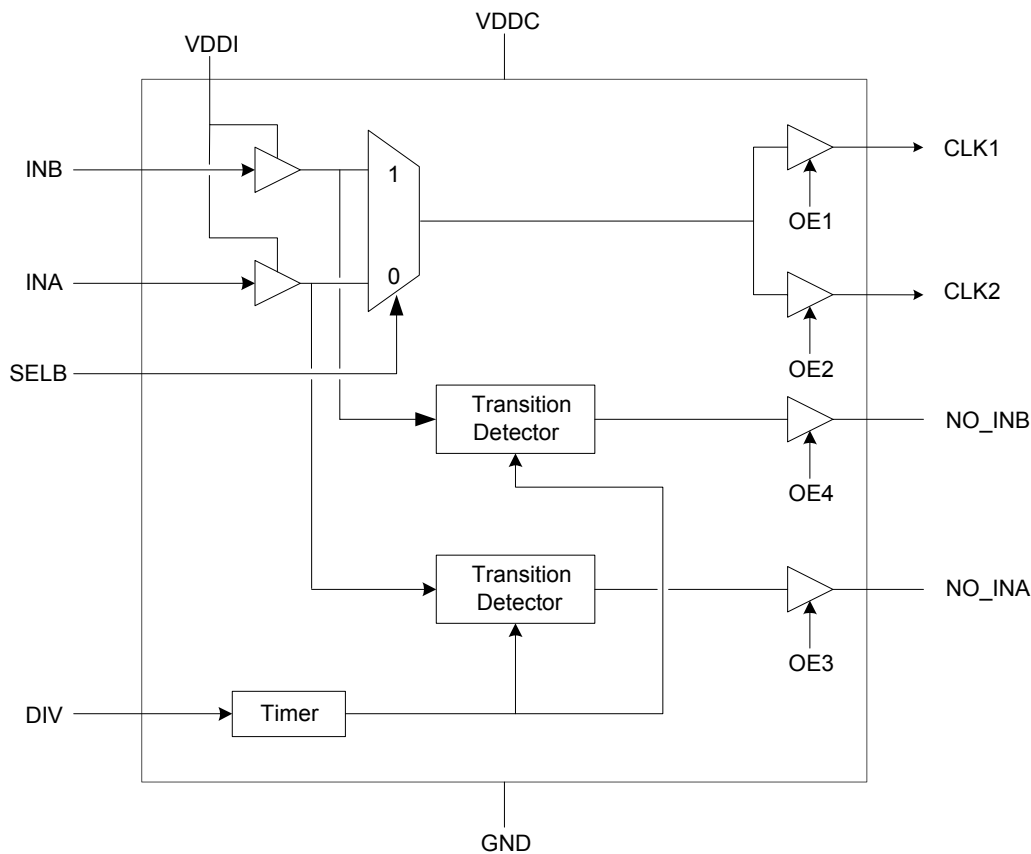
For a clock mux with zero delay and smooth switching, see either the ICS581-01 or the ICS581-02.

Features

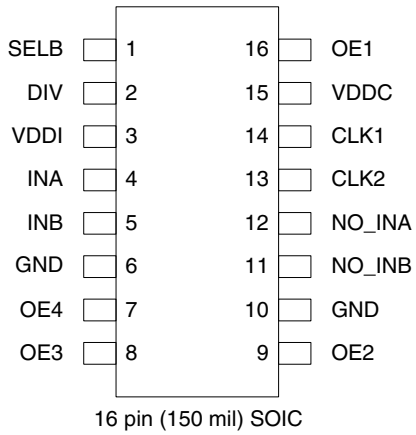
- 16-pin SOIC and 16-pin TSSOP packages available
- Available in Pb (lead) free package
- No short pulses or glitches on output
- Operates from 2 to 220 MHz
- Low skew outputs
- Clock detect feature
- Ideal for systems with back-up or redundant clocks
- Selectable timeouts for clock detection
- Separate supply voltages allow power supply voltage translation
- Operates from 2.5 V to 5 V

NOTE: EOL for non-green parts to occur on 5/13/10 per PDN U-09-01

Block Diagram

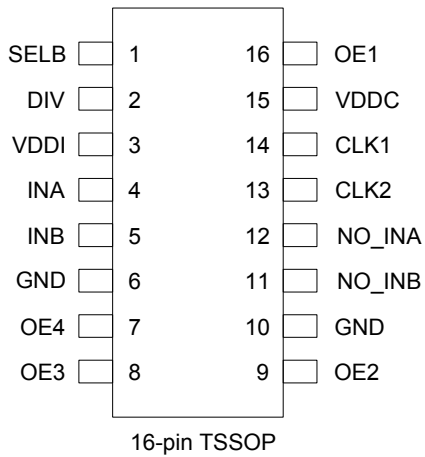


Pin Assignment



Timeout Selection

| DIV | Nominal Timeout |
|-----|-----------------|
| 0 | 600 ns |
| 1 | 75 ns |



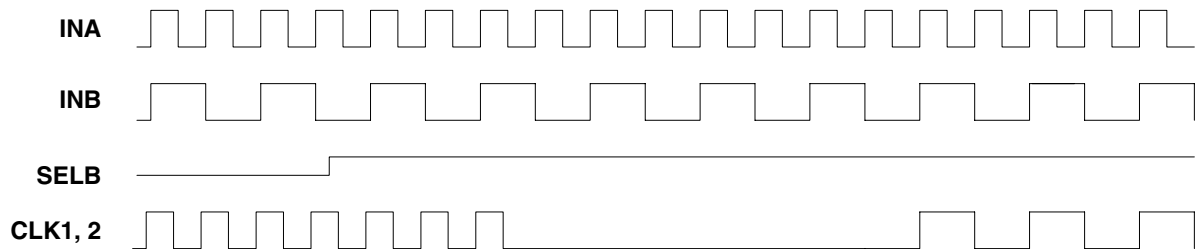
Pin Descriptions

| Pin Number | Pin Name | Pin Type | Pin Description |
|------------|----------|----------|--|
| 1 | SELB | Input | Mux select. Selects INB when high. Internal pull-up. |
| 2 | DIV | Input | Time out select. See table above. Internal pull-up. |
| 3 | VDDI | Power | Supply for input clocks only. Can be higher than VDDC. |
| 4 | INA | Input | Input Clock A. |
| 5 | INB | Input | Input Clock B. |
| 6 | GND | Power | Connect to ground. |
| 7 | OE4 | Input | Output enable. Tri-states NO_INB when low. Internal pull-up. |
| 8 | OE3 | Input | Output enable. Tri-states NO_INA when low. Internal pull-up. |
| 9 | OE2 | Input | Output enable. Tri-states CLK2 when low. Internal pull-up. |
| 10 | GND | Power | Connect to ground. |
| 11 | NO_INB | Output | Goes high when clock on INB stops. |
| 12 | NO_INA | Output | Goes high when clock on INA stops. |
| 13 | CLK2 | Output | Clock 2 output. Low skew compared to CLK1. |
| 14 | CLK1 | Output | Clock 1 output. Low skew compared to CLK2. |
| 15 | VDDC | Power | Main chip supply. Output clocks amplitude will match this VDD. |
| 16 | OE1 | Input | Output enable. Tri-states CLK1 when low. Internal pull-up. |

Device Operation

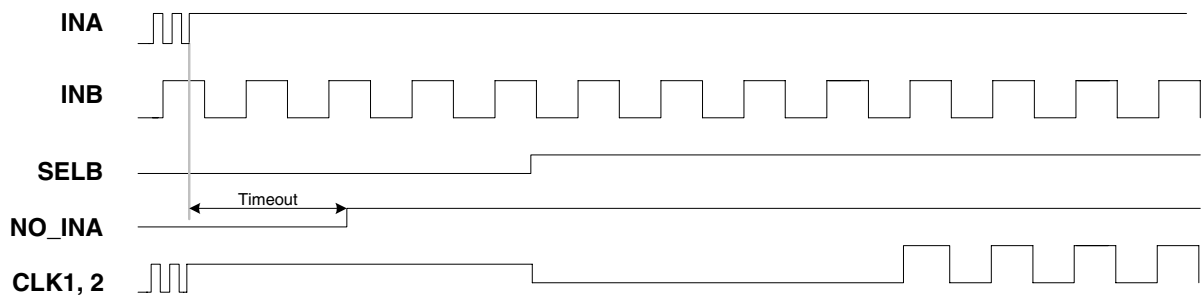
The ICS580-01 consists of a glitch free mux between INA and INB controlled by SELB. The device is designed to switch between two clocks, whether running or not. In the first example, clocks are running on both INA and INB. When SELB changes, the output clock goes low after three cycles of the output clock (nominally). The output then stays low for three cycles of the new input clock (nominally) and then starts with the new input clock. This is shown in Figure 1.

Figure 1



In the second example, one of the inputs was selected and running but has since stopped (either high or low). This is indicated by either NO_INA or NO_INB going high depending on whether INA or INB has stopped. These signals go high following a selectable time-out period after the clock has stopped. The timeout period is determined by the DIV input in. The SELB pin is now changed to select the new input clock which is running. The output clock immediately goes low and stays low for three cycles of the new input clock and then starts with the new input clock. Figure 2 shows an example of this

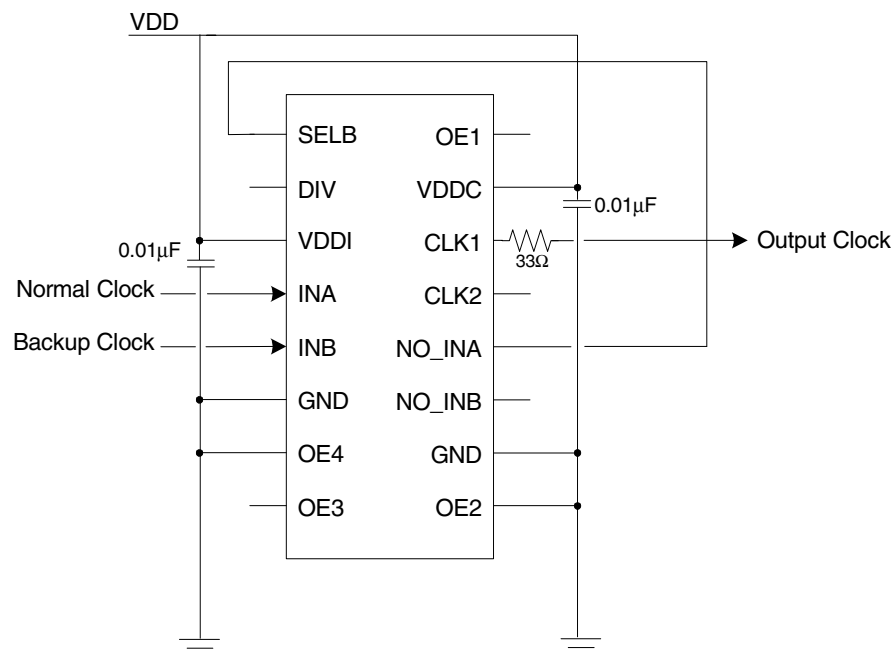
Figure 2



Application Example

In the third example, the ICS580-01 is configured to automatically switch clocks when an input stops. The clock that could stop is connected to INA while the backup clock (always running) is connected to INB. The output NO_INA is connected to SELB. This means that when the clock on INA stops, NO_INA goes high selecting the clock on INB which is muxed to the output after three cycles. When the clock on INA restarts, NO_INA immediately goes low, selecting the clock on INA. The output then switches in the manner described in the first example.

The circuit diagram in Figure 3 shows a typical connection for this example. Note that CLK2 and NO_INB are unused and are disabled by grounding OE2 and OE4. A 33Ω series termination resistor is used on the clock output and two decoupling capacitors of $0.01\mu\text{F}$ are used. All other inputs are left floating and are therefore pulled high by the on-chip pull-ups.



Output Enable

Each output has a dedicated output enable pin. If an output is unused, it should be tri-stated by tying the appropriate output enable pin to ground.

External Components

The ICS580-01 requires two $0.01\mu\text{F}$ decoupling capacitors, one between VDDI and GND and one between VDDC and GND. Series termination resistors of 33Ω can be used on CLK1 and CLK2.

Split Power Supplies

The VDDI pin provides the power for the INA and INB input buffers only. All the other inputs and the rest of the chip are connected to VDDC. This allows for supply voltage translation. For example, INA and INB could be 5V clocks (VDDI = 5V) and the rest of the chip could use a 3.3V supply on VDDC giving 3.3V output clocks. For correct operation VDDI must always be greater than or equal to VDDC.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the ICS580-01. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

| Item | Rating |
|-------------------------------|-------------------|
| Supply Voltage, VDD | 7V |
| All Inputs and Outputs | -0.5V to VDD+0.5V |
| Ambient Operating Temperature | 0 to +70° C |
| Ambient Operating Temperature | -40 to +85° C |
| Storage Temperature | -65 to +150° C |
| Junction Temperature | 125° C |
| Soldering Temperature | 260° C |

Recommended Operation Conditions

| Parameter | Min. | Typ. | Max. | Units |
|---|------|------|------|-------|
| Ambient Operating Temperature | 0 | | +70 | ° C |
| Ambient Operating Temperature | -40 | | +85 | ° C |
| Power Supply Voltage (measured in respect to GND) | +2.5 | | +5.5 | V |

DC Electrical Characteristics

Unless stated otherwise, VDD = 3.3V \pm 5%, Ambient Temperature -40 to +85° C

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Units |
|--------------------|-----------------|----------------------------|------------|------|------|-------|
| Operating Voltage | VDDC | | 2.5 | | 5.5 | V |
| | VDDI | | VDDC | | 5.5 | V |
| Supply Current | IDD | 50 MHz, no load | | 6 | | mA |
| Input High Voltage | V _{IH} | Non-clock inputs | 2 | | VDDC | V |
| Input Low Voltage | V _{IL} | Non-clock inputs | | | 0.8 | V |
| Input High Voltage | V _{IH} | INA and INB only Note 3 | (VDDC/2)+1 | | VDDI | V |

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Units |
|--------------------------|----------|--|---------------|----------|-----------------|------------|
| Input Low Voltage | V_{IL} | INA and INB only Note 3 | | | $(V_{DDC}/2)-1$ | V |
| Input Capacitance | C_{IN} | | | 4 | | pF |
| Output High Voltage | V_{OH} | $I_{OH} = -12$ mA | $V_{DDC}-0.5$ | | | V |
| Output Low Voltage | V_{OL} | $I_{OL} = 12$ mA | | | 0.5 | V |
| Short Circuit Current | I_{OS} | | | ± 70 | | mA |
| On-chip pull-up Resistor | R_{PU} | Non-clock inputs Pull-up to V_{DDC} | | 250 | | k Ω |

AC Electrical Characteristics

Unless stated otherwise, $V_{DD} = 3.3V \pm 5\%$, Ambient Temperature -40 to $+85^\circ$ C

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Units |
|---|----------|------------------------|-----------|------|------|-------|
| Input Frequency INA and INB, Note 1 | f_{IN} | $V_{DDC} = 5V$ | 1/timeout | | 270 | MHz |
| | | $V_{DDC} = 3.3V$ | 1/timeout | | 220 | MHz |
| | | $V_{DDC} = 2.7V$ | 1/timeout | | 180 | MHz |
| Propagation Delay INA or INB to output | | $V_{DDC} = 5V$ | | 4 | 8 | ns |
| | | $V_{DDC} = 3.3V$ | | 5 | 10 | ns |
| | | $V_{DDC} = 2.7V$ | | 6 | 12 | ns |
| Transition Detector Timeout, DIV = 0 | | $V_{DDI} = 5V$ | 175 | 350 | 750 | ns |
| | | $V_{DDI} = 3.3V$ | 500 | 1000 | 2000 | ns |
| | | $V_{DDI} = 2.7V$ | 750 | 1500 | 3000 | ns |
| Transition Detector Timeout, DIV = 1 | | $V_{DDI} = 5V$ | 20 | 40 | 80 | ns |
| | | $V_{DDI} = 3.3V$ | 55 | 110 | 210 | ns |
| | | $V_{DDI} = 2.7V$ | 100 | 200 | 400 | ns |
| Output Clock Rise Time | | | | | 1.5 | ns |
| Output Clock Fall Time | | | | | 1.5 | ns |
| Output Clock Skew | | CLK1 to CLK2 Note 2 | -250 | 0 | 250 | ps |

Note 1. Frequencies less than the minimum may cause a timeout which will not guarantee glitch-free switching unless the clock is actually stopped.

Note 2: Assumes identically loaded outputs with identical rise times, measured at $V_{DD}/2$.

Note 3: Output duty cycle is set by duty cycle of input clock at $V_{DDC}/2$.

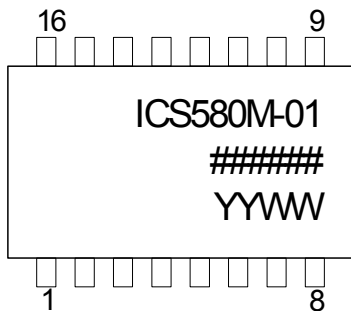
Thermal Characteristics (16-pin SOIC)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Units |
|--|---------------|----------------|------|------|------|-------|
| Thermal Resistance Junction to Ambient | θ_{JA} | Still air | | 120 | | °C/W |
| | θ_{JA} | 1 m/s air flow | | 115 | | °C/W |
| | θ_{JA} | 3 m/s air flow | | 105 | | °C/W |
| Thermal Resistance Junction to Case | θ_{JC} | | | 58 | | °C/W |

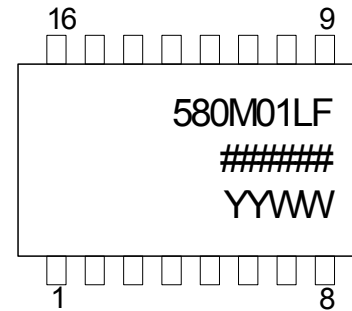
Thermal Characteristics (16-pin TSSOP)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Units |
|--|---------------|----------------|------|------|------|-------|
| Thermal Resistance Junction to Ambient | θ_{JA} | Still air | | 78 | | °C/W |
| | θ_{JA} | 1 m/s air flow | | 70 | | °C/W |
| | θ_{JA} | 3 m/s air flow | | 68 | | °C/W |
| Thermal Resistance Junction to Case | θ_{JC} | | | 37 | | °C/W |

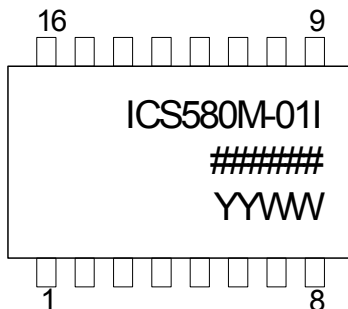
Marking Diagram (ICS580M-01)



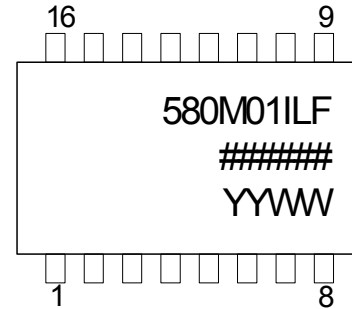
Marking Diagram (ICS580M-01LF)



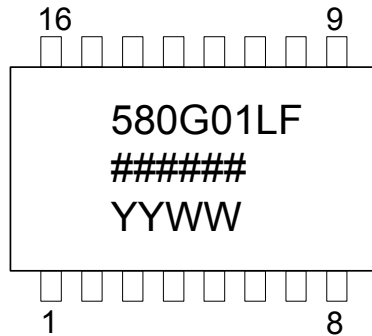
Marking Diagram (ICS580M-01I)



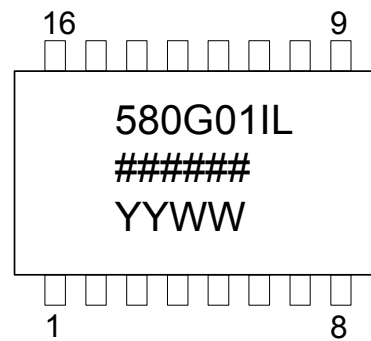
Marking Diagram (ICS580M-01ILF)



Marking Diagram (ICS580G-01LF)



Marking Diagram (ICS580G-01ILF)

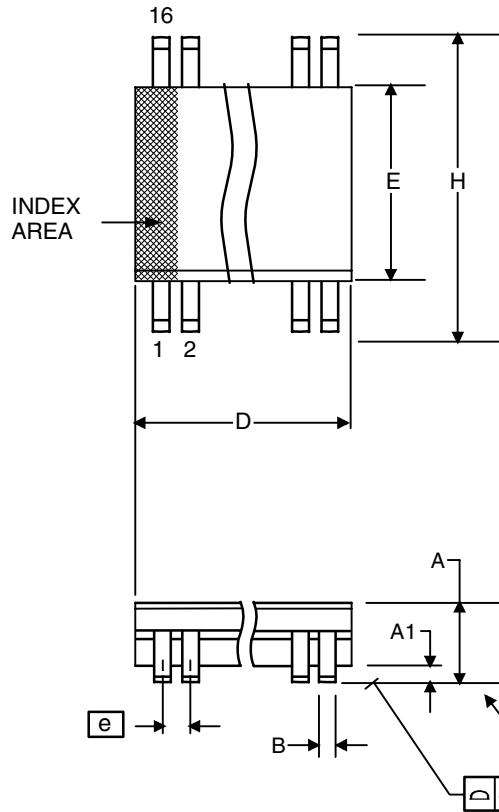


Notes:

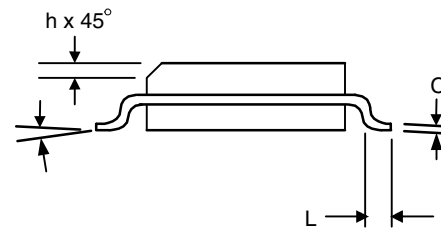
1. ##### is the lot number.
2. YYWW is the last two digits of the year and week that the part was assembled.
3. "LF" denotes Pb (lead) free package.
4. "I" indicates industrial grade.
4. Bottom marking: country of origin if not USA.

Package Outline and Package Dimensions (16-pin SOIC, 150 Mil. Narrow Body)

Package dimensions are kept current with JEDEC Publication No. 95

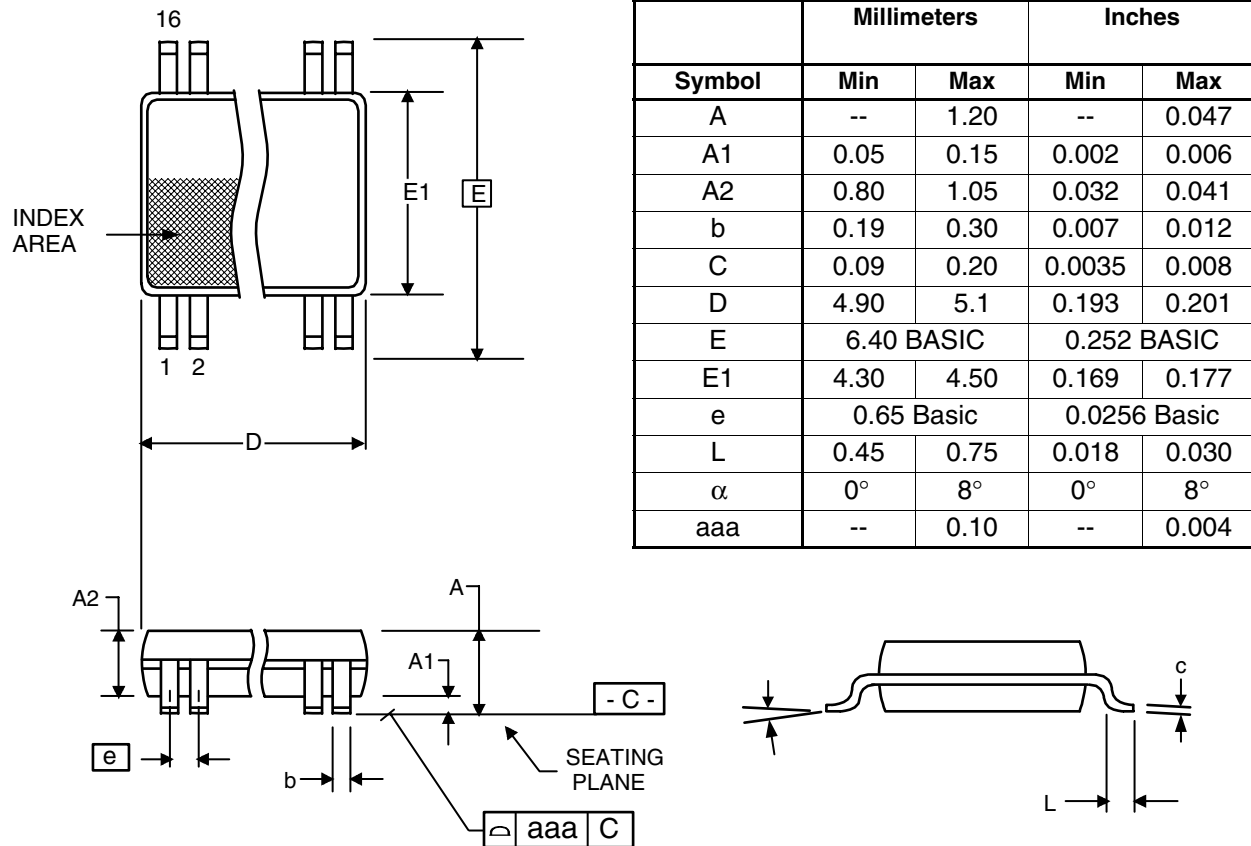


| Symbol | Millimeters | | Inches | |
|----------|-------------|-------|-------------|-------|
| | Min | Max | Min | Max |
| A | 1.35 | 1.75 | .0532 | .0688 |
| A1 | 0.10 | 0.25 | .0040 | .0098 |
| B | 0.33 | 0.51 | .013 | .020 |
| C | 0.19 | 0.25 | .0075 | .0098 |
| D | 9.80 | 10.00 | .3859 | .3937 |
| E | 3.80 | 4.00 | .1497 | .1574 |
| e | 1.27 BASIC | | 0.050 BASIC | |
| H | 5.80 | 6.20 | .2284 | .2440 |
| h | 0.25 | 0.50 | .010 | .020 |
| L | 0.40 | 1.27 | .016 | .050 |
| α | 0° | 8° | 0° | 8° |



Package Outline and Package Dimensions (16-pin TSSOP, 173 Mil. Body)

Package dimensions are kept current with JEDEC Publication No. 95



Ordering Information

| Part / Order Number | Marking | Shipping Packaging | Package | Temperature |
|---------------------|------------|--------------------|--------------|---------------|
| 580M-01* | see page 8 | Tubes | 16-pin SOIC | 0 to +70° C |
| 580M-01T* | | Tape and Reel | 16-pin SOIC | 0 to +70° C |
| 580M-01LF | | Tubes | 16-pin SOIC | 0 to +70° C |
| 580M-01LFT | | Tape and Reel | 16-pin SOIC | 0 to +70° C |
| 580M-01I* | | Tubes | 16-pin SOIC | -40 to +85° C |
| 580M-01IT* | | Tape and Reel | 16-pin SOIC | -40 to +85° C |
| 580M-01ILF | | Tubes | 16-pin SOIC | -40 to +85° C |
| 580M-01ILFT | | Tape and Reel | 16-pin SOIC | -40 to +85° C |
| 580G-01LF | see page 9 | Tubes | 16-pin TSSOP | 0 to +70° C |
| 580G-01LFT | | Tape and Reel | 16-pin TSSOP | 0 to +70° C |
| 580G-01ILF | | Tubes | 16-pin TSSOP | -40 to +85° C |
| 580G-01ILFT | | Tape and Reel | 16-pin TSSOP | -40 to +85° C |

***NOTE: EOL for non-green parts to occur on 5/13/10 per PDN U-09-01**

Parts that are ordered with a “LF” suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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